

# 4<sup>th</sup> Electronics Packaging Technology Conference (EPTC 2002)

10-12 December 2002

Grand Copthorne Waterfront Hotel, Singapore

## CALL FOR PAPERS



### About EPTC

The 4<sup>th</sup> Electronics Packaging Technology Conference (EPTC 2002) is organized by the IEEE Reliability/CPMT/ED Singapore Chapter with joint technical co-sponsorship from the IEEE Components, Packaging and Manufacturing Technology (CPMT) Society and International Microelectronics and Packaging Society (IMAPS).

The EPTC is an international conference dedicated to advances, research, development and applications of electronic components, assemblies and systems. Inaugurated in 1997, the EPTC is fast emerging as a major electronics packaging conference in South East Asia where the bulk of the world's packaging activities are taking place. It is the aim of the EPTC to offer quality and comprehensive coverage of technology innovation and development in electronic components and system packaging.

EPTC 2002 will feature technical sessions, short courses, and exhibition. It provides a platform to exchange knowledge and opportunities to network with and meet leading experts in the field.

### Conference Topics

You are invited to submit a paper presenting new development and state-of-the-art knowledge in the following categories:

- ❑ **Advanced Packaging:** New packaging technologies for single chip, multi-chip, wafer level, power and stacked-die packages addressing fine pitch, high I/O and performance issues.
- ❑ **Interconnection Technologies:** Wire bonding, flip chip (eutectic/lead-free solders), solder replacement flip chip (ICP, ACP, ACF, NCP), under bump metallurgy, high density substrates, microvia, build-up technologies, substrate metallurgy, embedded passives & actives, wafer/device level, MEMS, 3D and novel interconnects.
- ❑ **Materials & Processes:** Advances and application of adhesives, encapsulants, underfills, solder alloys, halogen-free materials, dielectrics, thin films, ceramics, composites, nano-materials, optical materials and characterization techniques.
- ❑ **Assembly & Manufacturing Technologies:** Wafer bumping, wafer thinning. Process characterization, yield improvement, cost and cycle time reduction.
- ❑ **Quality & Reliability:** Component, board and system level reliability assessment, failure analysis, interfacial adhesion, accelerated testings and models, component and system qualification.
- ❑ **Modeling & Simulation:** Electrical, thermal, thermo-mechanical, reliability, optical modeling and simulation for component and system level applications.
- ❑ **Optical and MEMS Packaging:** Optical component assemblies, electro-optical modules, waveguides, Inertial MEMS, RF, Optical & Bio MEMS.

### Important Dates

**20 July 2002**  
**20 August 2002**  
**10 October 2002**

### Extended Abstract Submission

**Submission of abstract**  
**Notification of Acceptance**  
**Submission of manuscript**

### Abstract and Paper Submission

Abstracts are solicited to describe original and unpublished work. The abstract should be about 500 words and it must clearly state the purpose, results (including data, drawings, graphs and photographs) and conclusion of the work. Key references to prior publications and how the work enhances existing knowledge should be included in the abstract as well.

Authors must designate two appropriate categories related to their work in their submission. All submissions must be in English and should be made via electronic mail to [eptc\\_ieee@pacific.net.sg](mailto:eptc_ieee@pacific.net.sg). The required file format is **Adobe Acrobat<sup>®</sup> PDF**, and only one single pdf file for each submission. Please limit the file size to a maximum of 2MB.

The abstracts must be received by **20 July 2002**. Authors must include their affiliation, mailing address, telephone and fax numbers, and email address. Authors will be notified of paper acceptance and publication instruction by **20 August 2002**. The final manuscript is due for publication in the conference proceedings by 10 October 2002.

### Outstanding Technical Papers

The conference proceedings will be an official IEEE publication. High quality papers will be considered for publication in a special issue of IEEE/CPMT Transactions. An "Outstanding Technical Paper" award will be presented to author(s) for a paper of exceptional quality.

### Short Courses and Exhibition

The conference program includes full-day short courses which will be conducted by leading experts in the field. Details will be updated in the conference website and available in the next mailing.

A tabletop exhibition featuring suppliers of materials, equipment, components, software and service providers of the microelectronics and electronic assembly industries will be held during the conference. For exhibition information and bookings, please contact the conference secretariat, *Ms Jasmine Leong*.

### Conference information & contacts

#### General Chair

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